

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2005/09/12 11:21
S2	2	S1 and (rate).clm.	US-PGPUB	OR	OFF	2005/09/12 11:13
S3	19	(US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-20050016947-\$).did. or (US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6628809-\$ or US-6643616-\$ or US-6728591-\$ or US-6757645-\$ or US-6763277-\$ or US-6774998-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$). did. or (US-5866437-\$ or WO-200177979-\$ or WO-200277589-\$ or US-20030135302-\$ or US-20040078319-\$ or US-20050010319-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/09/12 11:17
S4	19	(US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-20050016947-\$).did. or (US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6628809-\$ or US-6643616-\$ or US-6728591-\$ or US-6757645-\$ or US-6763277-\$ or US-6774998-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$). did. or (US-5866437-\$ or US-20030135302-\$ or US-20040078319-\$ or US-20050010319-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/09/13 14:11
S5	8	S4 and rate	US-PGPUB; USPAT	OR	OFF	2005/09/12 11:18
S6	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2005/09/12 11:21
S7	5	S6 and control\$6	US-PGPUB	OR	OFF	2005/09/12 11:22
S8	3	S6 and (control\$6).clm.	US-PGPUB	OR	OFF	2005/09/12 11:24
S9	2	S6 and (adjust\$6).clm.	US-PGPUB	OR	OFF	2005/09/12 11:23
S10	1	S6 and (nonlinear\$3 multivariate). clm.	US-PGPUB	OR	OFF	2005/09/12 11:25
S11	3	S3 and (nonlinear\$3 multivariate)	US-PGPUB	OR	OFF	2005/09/12 11:29
S12	1	S3 and (calibration)	US-PGPUB	OR	OFF	2005/09/12 11:30

S13	9	S3 and (adjust)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:33
S14	3	S3 and (converg\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:53
S15	4368	(ANSYS FLUENT CFRDC (Monte adj Carlo)) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:54
S16	213	(ANSYS) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 12:02
S17	3	(CFRDC) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:57
S18	612	(FLUENT) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:28
S19	1340	700/121.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:58
S20	156	(FLUENT) with simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:59

S21	84	(ANSYS) with simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 12:02
S22	118	(FLUENT) and simulat\$4 and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:29
S23	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2005/09/12 15:18
S24	19	(US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-20050016947-\$).did. or (US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6628809-\$ or US-6643616-\$ or US-6728591-\$ or US-6757645-\$ or US-6763277-\$ or US-6774998-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$). did. or (US-5866437-\$ or US-20030135302-\$ or US-20040078319-\$ or US-20050010319-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/09/12 18:26
S25	4	S24 and Geometric\$4	US-PGPUB; USPAT	OR	OFF	2005/09/12 18:27
S26	17208	(data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2005/09/12 18:29
S27	6771	S26 and (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2005/09/12 18:29
S28	1196	S26 and geometric	US-PGPUB; USPAT	OR	OFF	2005/09/12 18:29
S29	22	geometric with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2005/09/12 18:34
S30	70	geometric and (data parameter) with (etch deposition coating lithography (thermal adj annealing)) with (semionductor wafer)	US-PGPUB; USPAT	OR	OFF	2005/09/12 18:36
S32	2	(physical with geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2005/09/12 18:35

S33	5	(geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2005/09/12 18:35
S34	2	(input with size) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2005/09/12 18:37
S35	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2005/09/13 10:30
S36	50	("5886906" "5886363" "6031246" "6049661" "6095161" "4268951" "4782253" "5004774" "5446742" "6030491" "6168891" "6178544" "6207630" "4343878" "4443532" "4481049" "4491530" "4500798" "4530587" "4564921" "4581706" "4582683" "4597985" "4602153" "4615782" "4769817" "4792893" "4801713" "4822716" "4842986" "4873661" "4952666" "4969748" "4984902" "4989166" "4999282" "5006717" "5017453" "5059516" "5198520" "5213996" "5243538" "5248956" "5288604" "5312723" "5312724" "5330884" "5331420" "5336752" "5339039").pn.	USPAT	OR	OFF	2005/09/13 12:30
S37	50	("5340697" "5374327" "5382823" "5384289" "5400435" "5406309" "5409547" "5418397" "5427716" "5442644" "5455928" "5459020" "5474884" "5478702" "5490953" "5493501" "5495417" "5511005" "5517140" "5523022" "5558964" "5561612" "5571662" "5593608" "5596695" "5617322" "5619159" "5629877" "5637151" "5650947" "5654904" "5658706" "5663889" "5672468" "5672907" "5684723" "5694325" "5694052" "5699264" "5706200" "5709757" "5712794" "5714678" "5715170" "5725974" "5728514" "5731626" "5736024" "5737242" "5745388").pn.	USPAT	OR	OFF	2005/09/13 12:31
S38	7	(US-20050016947-\$).did. or (US-6625497-\$ or US-5629877-\$ or US-5377116-\$ or US-5719796-\$ or US-6802045-\$ or US-6812045-\$). did.	US-PGPUB; USPAT	OR	OFF	2005/09/13 12:46
S39	616	703/22.ccls.	US-PGPUB; USPAT	OR	OFF	2005/09/13 12:46

S40	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2005/09/13 12:54
S41	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2005/09/13 14:00
S42	5	S41 and empirical	US-PGPUB	OR	OFF	2005/09/13 14:00
S43	0	semiconductor with tool with emperical with model	US-PGPUB; USPAT	OR	OFF	2005/09/13 14:12
S44	0	(semiconductor with tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2005/09/13 14:12
S45	0	(processing with tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2005/09/13 14:12
S46	0	(semicondcutor and tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2005/09/13 14:12
S47	1	(tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2005/09/13 14:13
S48	5	(emperical with model)	US-PGPUB; USPAT	OR	OFF	2005/09/13 14:13